AMENDMENTS TO THE SPECIFICATION

Please amend Paragraphs 0018 and 0020 of the Specification as set forth below:

[0018] With reference to FIG. 3, there is illustrated a chemical-mechanical polisher 30 in accordance to one embodiment of the present invention. The polisher 30 includes a wafer carrier 32 for holding a semiconductor wafer 34 (e.g., 300 mm diameter) having a surface 36 to be polished. The wafer carrier 32 is mounted for continuous rotation about an axis [[~~34~~]]37 in a direction indicated by arrow [[~~36~~]]38 via a drive motor [[~~38~~]]39 operatively connected to the wafer carrier 32. The wafer carrier 32 is adapted so that a force indicated by arrow 40 is exerted on semiconductor wafer [[~~36~~]]34. The polisher 30 also includes a polishing platen 42 mounted for continuous rotation about an axis 44 in a direction indicated by an arrow 46 by a drive motor 48 operatively connected to the polishing platen 42. A polishing pad 50 is mounted to polishing platen 42. A polishing slurry containing an abrasive fluid is dispensed onto polishing pad 50 through a slurry dispensing arm 52 from temperature controlled reservoir 54. The slurry dispensing arm 52 is positioned adjacent to and above the polishing pad 50 and may be aligned radially with center of rotation of the polishing pad 50, which is centered on the axis 44. In other words, the longitudinal axis of the arm 52 may approximately intercept the axis 44. The polishing slurry is dispensed onto polishing pad 50 through the arm 52 from temperature controlled reservoir 54 as the wafer carrier 32 and polishing platen 42 rotate about their respective axes [[~~34~~]]37 and 44, with the slurry arm 52 remaining fix in location. The force between the polishing platen 42 and the wafer carrier 32 and their relative rotation, in combination with the mechanical abrasion and chemical effects of the slurry, serve to polish wafer surface 36.

[0020] Three embodiments (first, second and third embodiments) of the rinse delivery conduit are described hereinafter with respect to FIGS 4-7. The rinse delivery conduit has a proximate end and a distal end relative to the center of the pad. As compared to

the prior art embodiment of FIG. 1, these embodiments of the rinse delivery conduit have in common the achievement of a higher flow rate or flux (ml/min) at the proximate end of the rinse delivery conduit relative to the distal end, in order to compensate for the smaller pad velocities at inner radii of the inner circular regions of the pad 50. In other words, although the pad 50 may rotate at a constant angular speed, the velocity of pad 50 beneath a point of reference on the slurry dispensing arm 52 is decreased in proportion to the decrease in the distance between the reference point and the center 44 of the pad [[~~52~~]]50. This higher flow rate of the rinsing liquid is accomplished with optimized nozzle placement and inner diameter, as will be described hereinafter. Also, with respect to units of measure along the delivery conduit, e.g., inches, the flow rate/in at the proximate end is greater than the flow rate/in at the distal end.